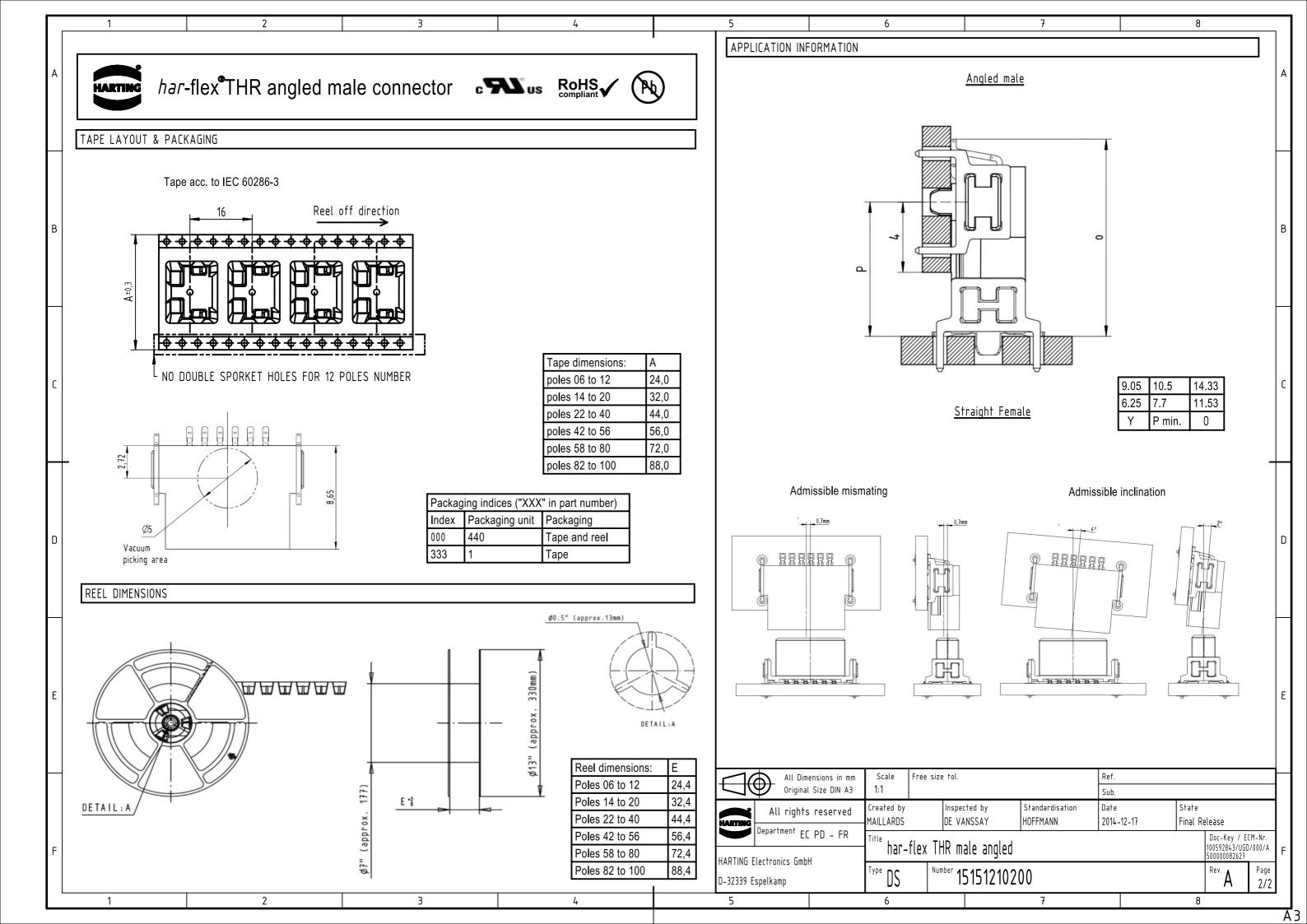
	1 2	3	4	ļ	5		6	7		8			
			D.110		RECOMMEN	ATION FOR	SOLDER PROCES	SING					
	har-flex THR angled male connector compliant → Rohar				Solder paste recommendation  The har-flex connectors are solderable with established lead-free SAC / SnNi solder but also leaded solder e.g. SnPb								
_													
GE	ENERAL INFORMATION			PCB pad plating									
_	lo. of contacts	from 6 to 100poles, all even	numhore		l — — · — · — ·		a aldorable on load	-free pad surfaces like HAL, NiA	u Immercian Cn				
_	Contact spacing	1,27mm x 1,27mm [0,050"x0			The har-nex c	onnectors are	soluerable on lead	-liee pau surfaces like HAL, INIA	u, illillersion Sii.				
_	est Voltage	500V	7,000 ]		Stencil recomi	mendation							
_	Contact resistance	<ul> <li>&lt; 25 mOhm</li> <li>≥ 10x10^9Ω</li> <li>see derating diagram</li> <li>-55°C +125°C</li> <li>SMT</li> <li>min. 150s &gt; 217°C</li> </ul>			The solder deposition has to be placed on the pad area of the contact solder tines.  Ideally, the solder deposition has the same length-to-width ratio and center point like the PCB pads.								
_	nsulation resistance												
_	Vorking current acc. to IEC 60512, at 70°C, 80% derating							ding on the thickness of the ster ertures to result in the required v		acto			
_	Vorking temperature range							he signal pins is 0,078mm³, for t					
_	ermination technology						nieved with the follo						
_	Reflow processing temperature				1								
(;	to ECA/IPC/JEDEC J-STD-075 Level PSL R0) min. 30s > 240°C			•	1	,		Signal pins					
C	Dearance & creepage distance	0.4mm min.			Stend	il thickness	PCB pad size	proposal stencil aperture size	calculated so	older paste volume			
Tr	nsertion force (depending on mating connector)	approximately 0,5N/contact				150 µm	0,8 x 0,8 mm	0,72 x 0,72 mm	0,	078 mm³			
_	Vithdrawal force (depending on mating connector)	approximately 0,5N/contact			]			Hold-downs					
٨	Mating cycles	PL1 : 500 mating cycles	<del></del>		<u> </u>	.01.41.1.1.	DOD = 1 1		1 . 1 . 1 . 1	alalan m = = 4:			
_		PL2 : 250 mating cycles			<b>├</b>	cil thickness	PCB pad size	proposal stencil aperture size		older paste volume			
_	RoHS - compliant	Yes				150 µm	Ø0,8 mm	Ø2,3 mm	1	.179 mm³			
_	eadfree	Yes											
_	Vorking voltage acc. to to IEC 60664-1 100V / 150V (depending on installation category)			If a stencil with lower thickness shall be used, please insure the minimum required solder paste volume by enlarging the stancil aparture. Depending on the PCR design, the solder deposition may protrude the PCR pade. But to achieve a great plant is a stancil aparture.									
1.1		ECBT2.E102079			tetonoil aporturo	Dononding	on the DCR decian	the colder denoction may pretry	stencil aperture. Depending on the PCB design, the solder depostion may protrude the PCB pads. But to achieve a go sealing during solder paste printing and to reduce the cleaning interval of the stencil, the aperture should be smaller				
_	JL file acc. UL 1977	•											
U	JL file acc. CSA-C22.2 (for Canada)	ECBT8.E102079			sealing during	solder paste p		ce the cleaning interval of the ste					
 	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075	ECBT8.E102079 PSL R0			sealing during s than the PCB p	solder paste p ad about 10%	printing and to reduc	ce the cleaning interval of the ste					
 	JL file acc. CSA-C22.2 (for Canada)	ECBT8.E102079			sealing during s than the PCB p Performance le	solder paste p ad about 10% vel	orinting and to reduct or 25µm encircliing	ce the cleaning interval of the ste g.					
U P N	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075	ECBT8.E102079 PSL R0			sealing during s than the PCB p Performance le Performance le Initial 250 matir	solder paste p ad about 10% vel vel 1 (recomn ng cycles, 10	orinting and to reduct or 25µm encircling nended for majority days gas test (25°C	te the cleaning interval of the step.  of applications)  1 / 75% r.h.) using H2S 10 ppb, N	ncil, the aperture	should be smaller 2 10 ppb, SO2 200 p			
P N	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075 JSL level acc. ECA/IPC/JEDEC J-STD-020D SULATOR MATERIAL	ECBT8.E102079 PSL R0 MSL 1	er)		sealing during sealing during sealing during sealing during sealing that the PCB performance lessealing lessealing during sealing seal	solder paste p ad about 10% vel vel 1 (recomn ng cycles, 10 f contact resi	orinting and to reduct or 25µm encircling nended for majority days gas test (25°C	te the cleaning interval of the sterms.  of applications)	ncil, the aperture	should be smaller 2 10 ppb, SO2 200 p			
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P NS NS	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075 MSL level acc. ECA/IPC/JEDEC J-STD-020D SULATOR MATERIAL Material Color	PSL R0 MSL 1  LCP (liquid crystalline polymer Black	er)		sealing during sealing during sealing during sealing than the PCB performance leading leading to the Performance leading leadi	vel vel (recomning cycles, 10 f contact resisection).	orinting and to reduce to a construction of the construction of th	of applications)  7 / 75% r.h.) using H2S 10 ppb, Ning 250 mating cycles are subjections.	IO2 200 ppb, CL2	should be smaller 2 10 ppb, SO2 200 p t of contact resistance			
	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075 MSL level acc. ECA/IPC/JEDEC J-STD-020D SULATOR MATERIAL Material Color JL classification	ECBT8.E102079 PSL R0 MSL 1  LCP (liquid crystalline polymer Black UL94-V0	er)		Performance le Performance le Initial 250 matir Measurement c and visual inspectic Part number de	solder paste pad about 10%  vel  vel 1 (recomn ng cycles, 10 f contact residection. on. No abrasic finition: 15	orinting and to reduce or 25µm encircling on 25µm encircling on ended for majority days gas test (25°C) stance. The remaining on of the contact finite.	of applications)  7 / 75% r.h.) using H2S 10 ppb, Ning 250 mating cycles are subjections.	IO2 200 ppb, CL2	should be smaller 2 10 ppb, SO2 200 p t of contact resistance			
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INS	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075 MSL level acc. ECA/IPC/JEDEC J-STD-020D SULATOR MATERIAL Material Color JL classification	ECBT8.E102079 PSL R0 MSL 1  LCP (liquid crystalline polymer Black UL94-V0	er)		sealing during sthan the PCB p Performance le Performance le Initial 250 matir Measurement cand visual inspection Part number de Performance le Initial 125 matir Measurement cand	vel vel 1 (recomning cycles, 10 of contact residention). No abrasic finition: 15 vel 2 og cycles, 4 def contact residention contact residention.	or inting and to reduce or 25µm encircling on 25µm encircling on ended for majority days gas test (25°C stance. The remaining on of the contact finition of the contact finiti	of applications)  7 / 75% r.h.) using H2S 10 ppb, Ning 250 mating cycles are subjections.	IO2 200 ppb, CL2 to measuremen No functional imp	2 10 ppb, SO2 200 pt of contact resistant pairment.			
INS INS CC U	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075 MSL level acc. ECA/IPC/JEDEC J-STD-020D SULATOR MATERIAL Material Color JL classification Material group acc. IEC 60664-1	ECBT8.E102079 PSL R0 MSL 1  LCP (liquid crystalline polymer Black UL94-V0	er)		sealing during sealing during sealing during sealing during sealing than the PCB performance led Initial 250 material visual inspection and visual inspection performance led Initial 125 material during and visual inspection and visual inspection sealing sealing during sealing during sealing during sealing sea	vel vel 1 (recomning cycles, 10 of contact residention. No abrasid finition: 15 ovel 2 or contact residention.	nended for majority days gas test (25°C ays gas tes	of applications)  of applications)  if 75% r.h.) using H2S 10 ppb, Noting 250 mating cycles are subjections through to the base material.  T75% r.h.) using H2S 10 ppb, Noting 125 mating cycles are subjecting 125 mating 125 mating cycles are subjecting 125 mating 1	IO2 200 ppb, CL2 to measuremen  D2 200 ppb, CL2 to measuremen	2 10 ppb, SO2 200 pt of contact resistance to pairment.			
INS CO	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075 MSL level acc. ECA/IPC/JEDEC J-STD-020D SULATOR MATERIAL Material Color JL classification Material group acc. IEC 60664-1 DNTACT MATERIAL Contact material Plating termination zone	ECBT8.E102079  PSL R0  MSL 1  LCP (liquid crystalline polymers)  Black  UL94-V0  Illa (175≤CTI< 400)  Copper alloy  Sn			sealing during sealing during sealing during sealing during sealing than the PCB performance less and visual inspection and visual inspection sealing limited and visual inspection and visual inspection sealing limited limi	solder paste pad about 10%  vel  vel 1 (recomning cycles, 10 of contact residention.  vel 2  vel 3  vel 2  vel 3  vel 4  vel 3  vel 3  vel 3  vel 3  vel 4  vel 3  vel 3  vel 4  vel 4  vel 4  vel 5  vel 6  vel 6  vel 7  vel 8  vel 9	nended for majority days gas test (25°C ays gas tes	of applications)  of 75% r.h.) using H2S 10 ppb, Noting 125 mating cycles are subjective through to the base material.	IO2 200 ppb, CL2 to measuremen  D2 200 ppb, CL2 to measuremen	2 10 ppb, SO2 200 pt of contact resistance to pairment.			
INS INS CC U M CCC	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075 MSL level acc. ECA/IPC/JEDEC J-STD-020D  SULATOR MATERIAL Material Color JL classification Material group acc. IEC 60664-1  DNTACT MATERIAL Contact material	ECBT8.E102079  PSL R0  MSL 1  LCP (liquid crystalline polymer Black  UL94-V0  Illa (175 ≤ CTI < 400)  Copper alloy			sealing during sealing during sealing during sealing during sealing than the PCB performance less and visual inspection of the PCB performance les and visual inspection of the PCB performance les and visual inspection of the PCB performance less and visual inspection of the PCB perform	solder paste pad about 10%  vel  vel 1 (recomning cycles, 10 of contact residection.  on. No abrasic finition: 15  vel 2  ng cycles, 4 doff contact residection.  on. No abrasic finition: 15	or inting and to reduce for 25µm encircling mended for majority days gas test (25°C stance. The remaining the contact finition of the contact finition.	of applications)  of 75% r.h.) using H2S 10 ppb, Noting 125 mating cycles are subjective through to the base material.	IO2 200 ppb, CL2 to measuremen  D2 200 ppb, CL2 to measuremen	2 10 ppb, SO2 200 pt of contact resistance to pairment.			
	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075 MSL level acc. ECA/IPC/JEDEC J-STD-020D SULATOR MATERIAL Material Color JL classification Material group acc. IEC 60664-1 DNTACT MATERIAL Contact material Plating termination zone	ECBT8.E102079  PSL R0  MSL 1  LCP (liquid crystalline polymers)  Black  UL94-V0  Illa (175≤CTI< 400)  Copper alloy  Sn			sealing during sealing during sealing during sealing during sealing than the PCB performance le Initial 250 matinal visual inspection Part number de Initial 125 matinal 125 matinal visual inspection Part number de Performance le Performance le Performance le	solder paste pad about 10%  vel  vel 1 (recomn ng cycles, 10 of contact resisection. on. No abrasic finition: 15  vel 2 ng cycles, 4 d of contact resisection. on. No abrasic finition: 15  vel 2 ng cycles, 4 d of contact resisection. on. No abrasic finition: 15	or inting and to reduce or 25µm encircling and to reduce on 25µm encircling and to reduce on 200 and the contact finition of the contact finition	of applications) of applications) of 75% r.h.) using H2S 10 ppb, Noting 250 mating cycles are subjectish through to the base material.  75% r.h.) using H2S 10 ppb, Noting 125 mating cycles are subjectish through to the base material.	IO2 200 ppb, CL2 to measuremen  D2 200 ppb, CL2 to measuremen	2 10 ppb, SO2 200 pt of contact resistance to pairment.			
	JL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075 MSL level acc. ECA/IPC/JEDEC J-STD-020D SULATOR MATERIAL Material Color JL classification Material group acc. IEC 60664-1 DNTACT MATERIAL Contact material Plating termination zone Plating contact sliding side	ECBT8.E102079  PSL R0  MSL 1  LCP (liquid crystalline polymers)  Black  UL94-V0  Illa (175≤CTI< 400)  Copper alloy  Sn			sealing during sealing during sealing during sealing during sealing than the PCB performance le Initial 250 matin Measurement of and visual inspection Part number despersional inspection and visual inspection Part number despersional inspection P	solder paste pad about 10%  vel  vel 1 (recomning cycles, 10 of contact residention.  on. No abrasic finition: 15  vel 2  ng cycles, 4 do f contact residention.  on. No abrasic finition: 15  vel 2  vel 3  vel 4 do f contact residention.  on. No abrasic finition: 15  vel S4  is surface of m	nended for majority days gas test (25°C astance. The remaining and to reduce the contact finition of t	of applications) of applications) of 75% r.h.) using H2S 10 ppb, Noting 250 mating cycles are subjections through to the base material.  75% r.h.) using H2S 10 ppb, Noting 125 mating cycles are subjections through to the base material.	IO2 200 ppb, CL2 to measuremen  D2 200 ppb, CL2 to measuremen	2 10 ppb, SO2 200 pt of contact resistance to pairment.			
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INS COUNTY P	PL file acc. CSA-C22.2 (for Canada) PSL level acc. ECA/IPC/JEDEC J-STD-075 PSL level acc. ECA/IPC/JEDEC J-STD-020D  SULATOR MATERIAL  Material Color PL classification  Material group acc. IEC 60664-1  DNTACT MATERIAL  Contact material Plating termination zone Plating contact sliding side  ERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacity)  The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals.  The current capacity curve is valid for continuous, non interrupted current loaded contacts of connectors when	ECBT8.E102079  PSL R0  MSL 1  LCP (liquid crystalline polymer Black  UL94-V0  Illa (175 ≤ CTI < 400)  Copper alloy  Sn  Au over PdNi (acc. to Perform	mance level)		Performance le Initial 250 matir Measurement dand visual inspection Part number de Performance le Initial 125 matir Measurement dand visual inspection Part number de Performance le Initial 125 matir Measurement dand visual inspection Part number de Performance le Defined contact Part number de Part number	solder paste pad about 10%  vel  vel 1 (recomning cycles, 10 of contact residention.  on. No abrasic finition: 15  vel 2 og cycles, 4 doff contact residention.  on. No abrasic finition: 15  vel 34  it surface of modifinition: 15	or 25µm encircling and to reduce for 25µm encircling and to reduce for 25µm encircling and 25°C astance. The remaining on of the contact finition of t	te the cleaning interval of the step.  of applications)  of 775% r.h.) using H2S 10 ppb, Noting 250 mating cycles are subjections through to the base material.  of 75% r.h.) using H2S 10 ppb, Noting 125 mating cycles are subjections through to the base material.  of 75% r.h.) using H2S 10 ppb, Noting 125 mating cycles are subjections through to the base material.	IO2 200 ppb, CL2 It to measuremen No functional imp D2 200 ppb, CL2 It to measuremen No functional imp	2 10 ppb, SO2 200 pt of contact resistance to pairment.			
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